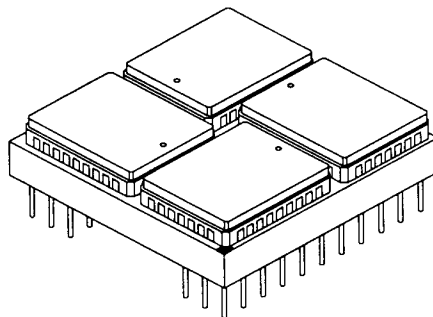


DESCRIPTION:

The DPS832V is a 66-pin Pin Grid Array (PGA) consisting of four 8K X 8 SRAM devices in ceramic LCC packages surface mounted on a co-fired ceramic substrate with matching thermal coefficients. The LCCs are mounted in a rotary pattern resulting in the smallest possible module outline.

The pins have been arranged around a central 0.6" gap which can accommodate a heat rail. In this central gap is a cavity containing four 0.1µf decoupling capacitors.

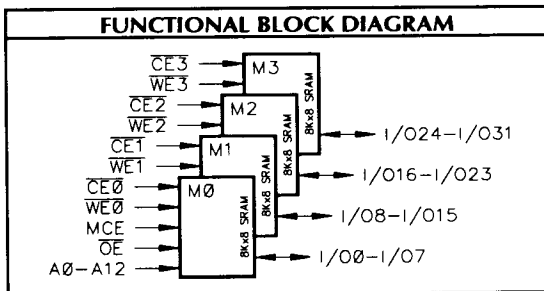
Provisions have been made in the pinout for use of 256K and 1MB SRAMs, providing an upgrade path to 128KX32 and to 256KX32 increasing the module density from four to thirty-two times.



4

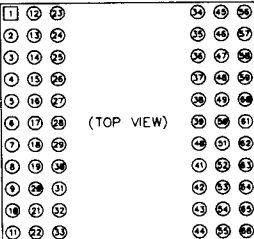
FEATURES:

- Organizations Available:
32K X 8, 16K X 16 or 8K X 32
- Access Times:
-25, -35, -45, -55, -70, -85, -100, -120, -150ns
- Low Data Retention: 2.0V min.
- Fully Static Operation - No clock or refresh required
- TTL-compatible
- 66-Pin PGA (Pin Grid Array) Package
- Same Package as other Versapac Versions (EEPROM, EPROM AND MIXED)
- Module Weight is 15 grams
- Module can be built with devices compliant to MIL-STD 883C



PIN NAMES	
A0 - A12	Address Inputs
I/O0 - I/O31	Data In/Out
CE0 - CE3	Chip Enables
MCE	Master Chip Enable
WE0 - WE3	Write Enables
OE	Output Enable
VDD	Power (+5V)
VSS	Ground
N.C.	No Connect

PIN-OUT DIAGRAM

1 I/O8	12 WET	23 I/O15	 <p>(TOP VIEW)</p>	34 I/O24	45 VDD	56 I/O31
2 I/O9	13 CET	24 I/O14		35 I/O25	46 CE3	57 I/O30
3 I/O10	14 VSS	25 I/O13		36 I/O26	47 WE3	58 I/O29
† 4 MCE	15 I/O11	26 I/O12		37 A6	48 I/O27	59 I/O28
* 5 N.C.	16 A10	27 OE		38 A7	49 A3	60 A0
* 6 N.C.	17 A11	28 N.C.		39 N.C.	50 A4	61 A1
* 7 N.C.	18 A12	29 WE0		40 A8	51 A5	62 A2
8 N.C.	19 VDD	30 I/O7		41 A9	52 WE2	63 I/O23
9 I/O0	20 CE0	31 I/O6		42 I/O16	53 CE2	64 I/O22
10 I/O1	21 N.C.	32 I/O5		43 I/O17	54 VSS	65 I/O21
11 I/O2	22 I/O3	33 I/O4		44 I/O18	55 I/O19	66 I/O20

* Designers should connect these pins to A13, 14, A15 and A16 for future upgrades.
 † To enable 8Kx8 SRAM pin 4 (MCE) must be held in logic '1' condition.

FOR FURTHER INFORMATION
SEE CHAPTER 10
FOR COMPLETE DATA SHEET